

SMTAK3 Series





Agency Recognitions

Agency	Agency File Number
<i>71</i> 2	E128662

Maximum Ratings and Thermal Characteristics (T_a=25°C unless otherwise noted)

Parameter	Symbol	Value	Unit
Operating Storage Temperature Range	T _{STG}	-55 to 150	°C
Operating Junction Temperature Range	T _J	-55 to 125	°C
Current Rating ¹	I _{PP}	3	kA

Note:

1. Rated I_{PP} measured with 8/20µs pulse.

Description

The SMTAK3 series of high current transient suppressors have been specially designed for use in D.C. line protection and any demanding applications. They offer superior clamping characteristics over standard S.A.D. technologies by virtue of the Littelfuse Foldbak technology. Therefore, any voltage rise due to increased current conduction is contained to a minimum, providing the best possible protection level.

Features

- Very low clamping voltage
- Sharp breakdown voltage
- Low slope resistance
- Bi-directional
- Foldbak technology for superior clamping factor
- Symmetric in leads width for easier soldering during assembly.
- IEC 61000-4-2 ESD 15kV(Air), 8kV (Contact)
- ESD protection of data lines in accordance with IEC 61000-4-2

- EFT protection of data lines in accordance with IEC 61000-4-4
- Halogen-free
- RoHS compliant
- Glass passivated junction
- Pb-free E4 means 2nd level interconnect is Pb-free and the terminal finish material is silver (IPC/JEDEC J-STD-609A.01)
- UL Recognized to ANSI/ UL 497B

Functional Diagram



Electrical Characteristics (T_a=25°C unless otherwise noted)

Part Numbers	Part Marking	Standoff Voltage (V _{so}) Volts	Max. Reverse Leakage (I _R) @V _{so}	Typical I _R @ 85°C (μΑ)	Reve Breake Voltaç (Volts	down je V _{BR}	Test Current I _T	Current V _{CL} @ I _{pp} Peak Pulse		Max. Temp Coefficient OF V _{BR}		Agency Approval
			μΑ	'' '	Min	Max	(mA)	V _{CL} Volts	I _{PP} Amps	(%/°C)	(nF)	
SMTAK3-015C	S3-015C	15	10	15	16	19	10	28	3,000	0.1	9.0	Х
SMTAK3-058C	S3-058C	58	10	15	64	70	10	110	3,000	0.1	6.0	X
SMTAK3-066C	S3-066C	66	10	15	72	80	10	120	3,000	0.1	6.0	Χ
SMTAK3-076C	S3-076C	76	10	15	85	95	10	140	3,000	0.1	6.0	X

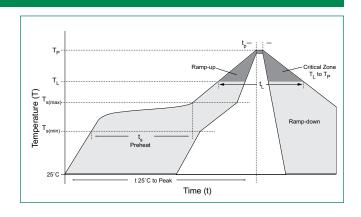
Note

1. Using 8/20µs wave shape as defined in IEC 61000-4-5.



Soldering Parameters

Reflow Con	dition	Lead-free assembly	
	-Temperature Min (T _{s(min)})	150°C	
Pre Heat	-Temperature Max (T _{s(max)})	200°C	
	-Time (min to max) (t _s)	60 – 120 secs	
Average rar peak	mp up rate (Liquidus Temp (T _A) to	3°C/second max	
T _{S(max)} to T _A	- Ramp-up Rate	3°C/second max	
Reflow	-Temperature (T _L) (Liquidus)	217°C	
nellow	-Time (min to max) (t _s)	60 – 150 seconds	
Peak Tempe	erature (T _P)	260+0/-5 °C	
Time within (t _p)	n 5°C of actual peak Temperature	30 seconds max	
Ramp-dow	n Rate	6°C/second max	
Time 25°C 1	to peak Temperature (T _P)	8 minutes Max.	
Do not exce	eed	260°C	



Flow/Wave Soldering (Solder Dipping)

Peak Temperature :	265°C
Dipping Time :	10 seconds
Soldering :	1 time

Physical Specifications

Weight	Contact manufacturer		
Case	Compound encapsulated		
Terminal	Silver plated leads, solderable per MIL-STD-202 Method 208		

Wave Solder Profile

Figure 1 - Non Lead-free Profile

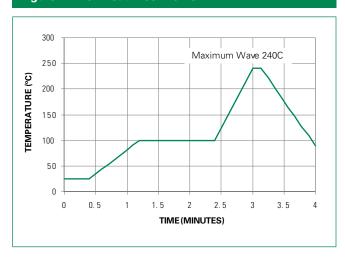
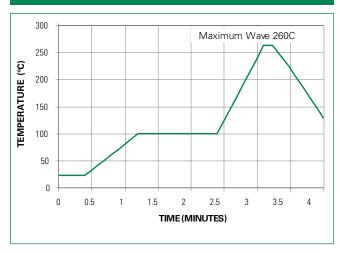


Figure 2 - Lead-free Profile





Ratings and Characteristic Curves (T_a=25°C unless otherwise noted)

Figure 3 - Peak Power Derating

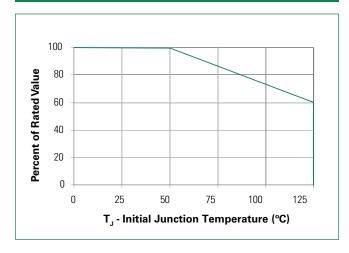


Figure 5 - Typical V_{RR} Vs Junction Temperature

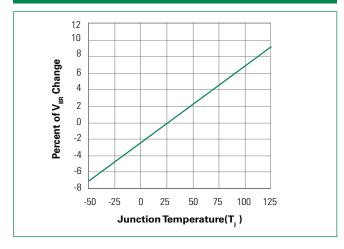


Figure 7 - Pulse Waveform

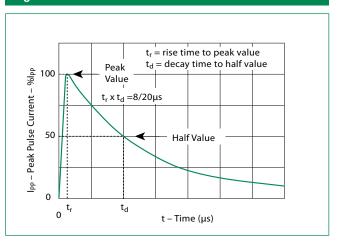


Figure 4 - Typical Peak Pulse Power Rating Curve

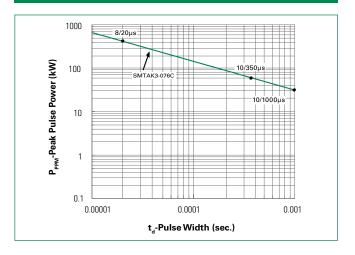
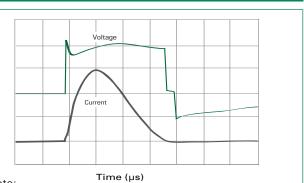


Figure 6 -Surge Response (8/20 Surge current waveform)

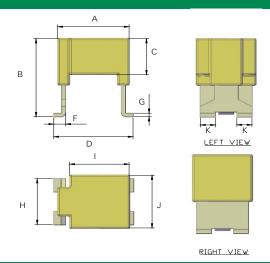


Note:

The power dissipation causes a change in avalanche voltage during the surge and the avalanche voltage eventually returns to the original value when the transient has passed.

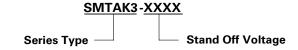


Dimensions

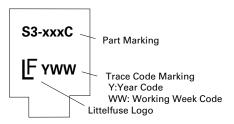


Dimensions	Inches	Millimeters		
А	0.354 +0.059/- 0.020	9.0 +1.5/- 0.5		
B-SMTAK3-015C	0.362 +/- 0.059	9.2 +/- 1.5		
B-SMTAK3-058C/ 066C/076C	0.394 +/- 0.039	10.0 +/- 1.0		
C-SMTAK3-015C	0.205 REF	5.2 REF		
C-SMTAK3-058C/ 066C/076C	0.264 REF	6.7 REF		
D	0.366 +/- 0.020	9.3 +/- 0.5		
F	0.045 +/- 0.012	1.15 +/- 0.3		
G	0.020 +/- 0.008	0.5 +/- 0.2		
Н	0.256 +/- 0.020	6.5 +/- 0.5		
I	0.319 REF	8.1 REF		
J	0.295 +0.059/- 0.020	7.5 +1.5/- 0.5		
K	0.075 +/- 0.020	1.9 +/- 0.5		

Part Numbering System



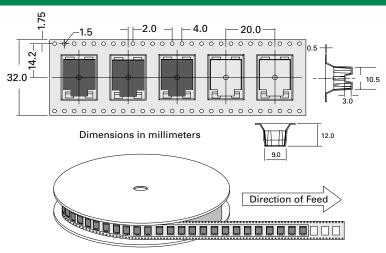
Part Marking System



Packing Options

Part Number	Component Package	Packing Mode	Quantity
SMTAK3-xxxC	SMTAK Package	Tape & Reel – 32mm/13" tape	200
SMTAK3-xxxC-B	SMTAK Package	Bulk	100

Tape and Reel Specification



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